

MBR130, NRVB130

Schottky Power Rectifier, Surface Mount

1.0 A, 30 V, SOD-123 Package

This device uses the Schottky Barrier principle with a large area metal-to-silicon power diode. Ideally suited for low voltage, high frequency rectification or as free wheeling and polarity protection diodes in surface mount applications where compact size and weight are critical to the system. This package also provides an easy to work with alternative to leadless 34 package style.

Features

- Guardring for Stress Protection
- Low Forward Voltage
- 125°C Operating Junction Temperature
- Epoxy Meets UL 94 V-0 @ 0.125 in
- Package Designed for Optimal Automated Board Assembly
- ESD Rating:
 - ♦ Human Body Model = 3
 - ♦ Machine Model = C
- NRVB Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These are Pb-Free Packages*

Mechanical Characteristics

- Device Marking: S3
- Polarity Designator: Cathode Band
- Weight: 11.7 mg (approximately)
- Case: Epoxy, Molded
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds



ON Semiconductor®

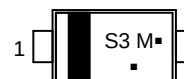
<http://onsemi.com>

**SCHOTTKY BARRIER
RECTIFIER
1.0 AMPERES
30 VOLTS**



**SOD-123
CASE 425
STYLE 1**

MARKING DIAGRAM



S3 = Specific Device Code
M = Date Code
▪ = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping [†]
MBR130T1G, NRVB130T1G	SOD-123 (Pb-Free)	3,000 / Tape & Reel **
MBR130T3G, NRVB130T3G	SOD-123 (Pb-Free)	10,000 / Tape & Reel ***

** 8 mm Tape, 7" Reel

*** 8 mm Tape, 13" Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

MBR130, NRVB130

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM} V_{RWM} V_R	30	V
Average Rectified Forward Current (Rated V_R) $T_L = 65^\circ\text{C}$	$I_{F(AV)}$	1.0	A
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions, Halfwave, Single Phase, 60 Hz)	I_{FSM}	5.5	A
Storage Temperature Range	T_{stg}	-65 to +125	$^\circ\text{C}$
Operating Junction Temperature	T_J	-65 to +125	$^\circ\text{C}$
Voltage Rate of Change (Rated V_R)	dv/dt	1000	V/ μs

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction to Ambient (Note 1)	$R_{\theta JA}$	230	$^\circ\text{C/W}$
Thermal Resistance, Junction to Lead (Note 1)	$R_{\theta JL}$	108	$^\circ\text{C/W}$

1. FR-4 or FR-5 = 3.5×1.5 inches using a 1 inch Cu pad.

ELECTRICAL CHARACTERISTICS

Characteristic	Symbol	Typ	Max	Unit
Instantaneous Forward Voltage (Note 2) ($I_F = 0.1$ A, $T_J = 25^\circ\text{C}$) ($I_F = 0.7$ A, $T_J = 25^\circ\text{C}$) ($I_F = 1.0$ A, $T_J = 25^\circ\text{C}$)	V_F	– – 0.47	0.35 0.45 –	V
Maximum Instantaneous Reverse Current (Note 2) (Rated DC Voltage, $T_C = 25^\circ\text{C}$) ($V_R = 5$ V, $T_C = 25^\circ\text{C}$)	I_R	60 10		μA

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

2. Pulse Test: Pulse Width = 300 μs , Duty Cycle $\leq 2\%$.

MBR130, NRVB130

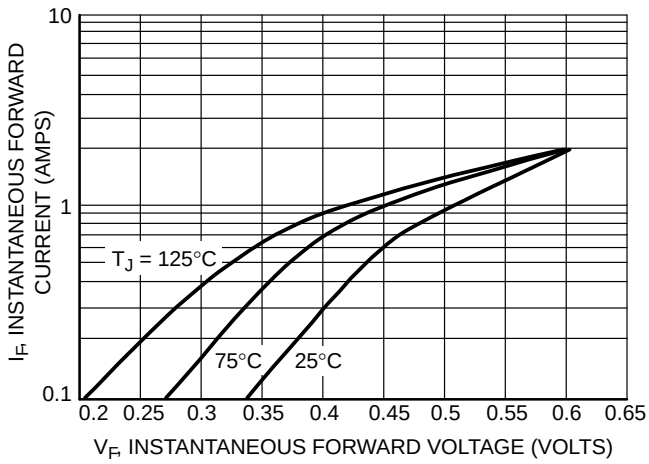


Figure 1. Maximum Forward Voltage

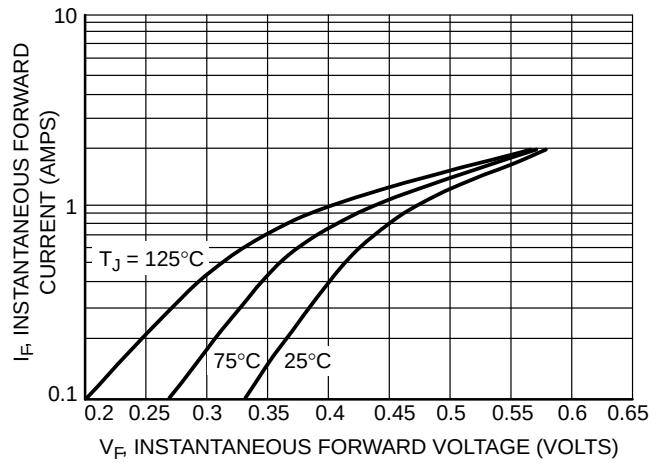


Figure 2. Typical Forward Voltage

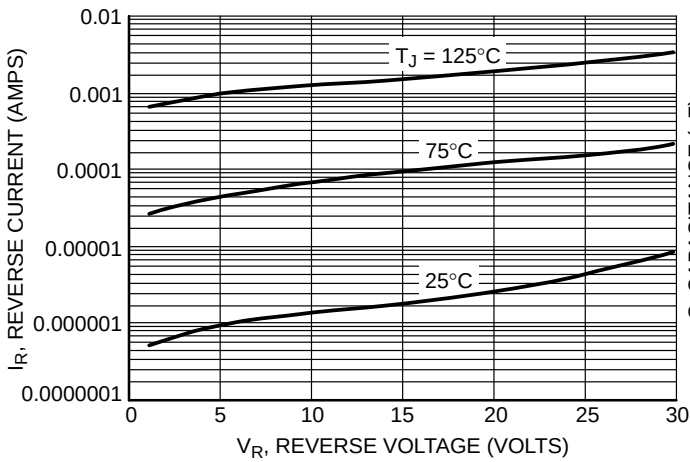


Figure 3. Typical Reverse Current

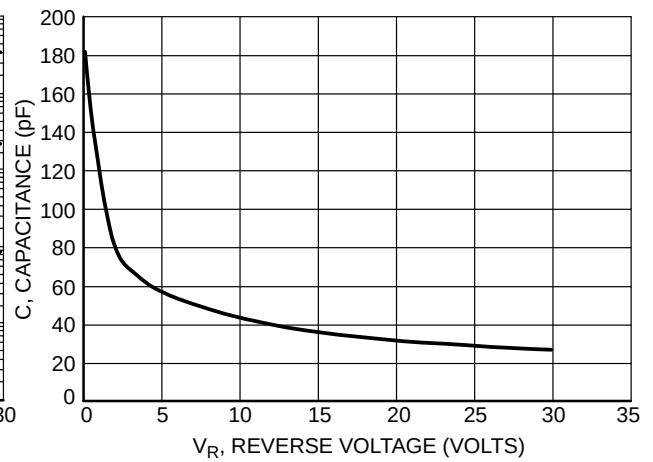


Figure 4. Typical Capacitance

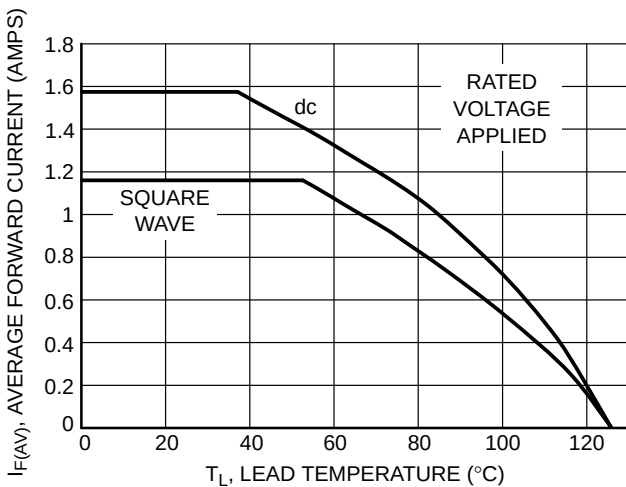


Figure 5. Current Derating, Lead, $R_{\theta_{JL}} = 108^{\circ}\text{C/W}$

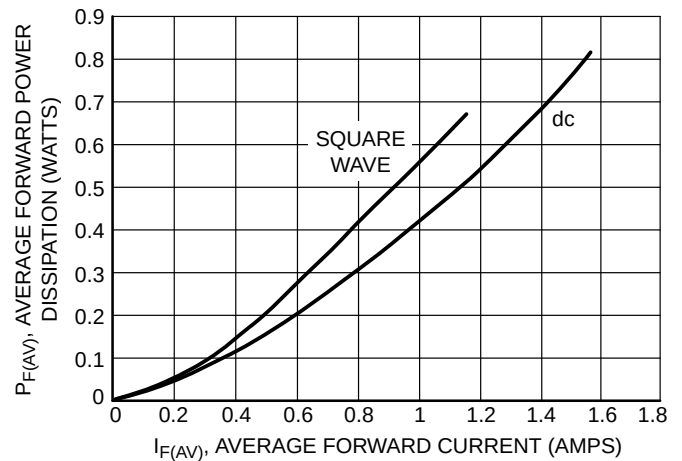
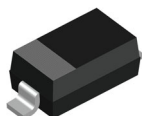


Figure 6. Forward Power Dissipation

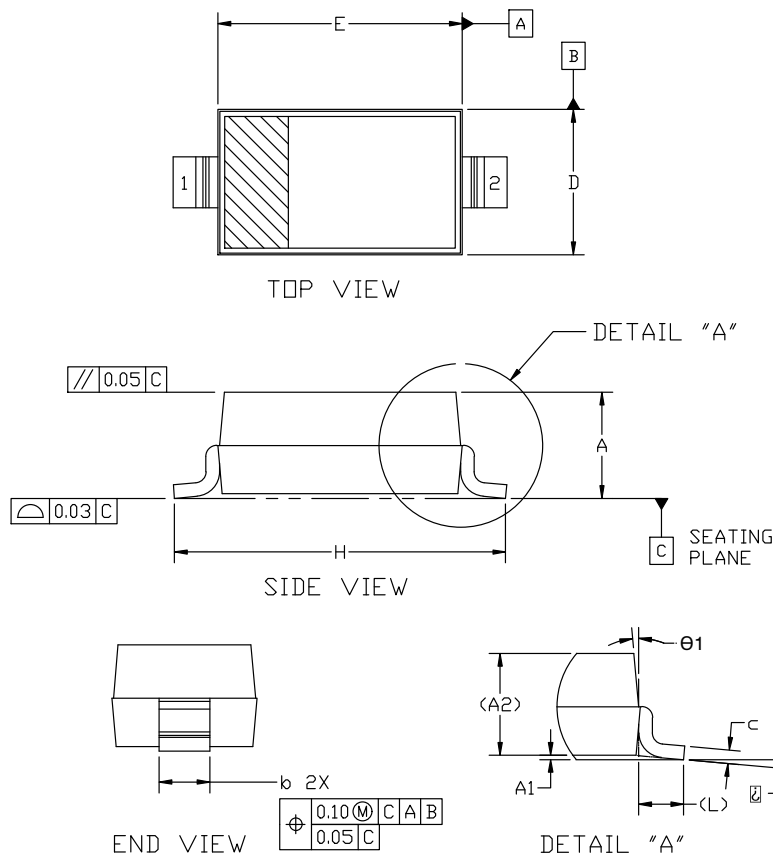


SOD-123 2-LEAD, 1.60x2.69x1.16

CASE 425

ISSUE H

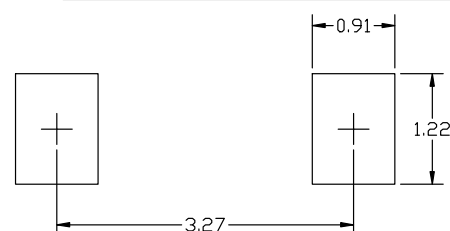
DATE 29 FEB 2024



NOTES:

1. DIMENSION AND TOLERANCING PER ASME Y14.5M, 2018
2. CONTROLLING DIMENSION: MILLIMETERS

	MILLIMETER		
DIM	MIN.	NOM.	MAX.
A	0.94	1.17	1.35
A1	0.00	0.05	0.10
A2	1.16 REF.		
b	0.51	0.61	0.71
c	—	—	0.15
D	1.40	1.60	1.80
E	2.54	2.69	2.84
H	3.56	3.68	3.86
L	0.25 REF.		
	0°		10°
Ø1	0°		10°



GENERIC MARKING DIAGRAM*



XXX = Specific Device Code

M = Date Code

- = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

STYLE 1:
PIN 1. CATHODE
2. ANODE

RECOMMENDED MOUNTING FOOTPRINT

*For additional information on or Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference manual
SOLDDRM/D.

DOCUMENT NUMBER:	98ASB42927B	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
DESCRIPTION:	SOD-123 2-LEAD, 1.60x2.69x1.16	PAGE 1 OF 1

onsemi and **onsemi** are trademarks of Semiconductor Components Industries, LLC dba **onsemi** or its subsidiaries in the United States and/or other countries. **onsemi** reserves the right to make changes without further notice to any products herein. **onsemi** makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does **onsemi** assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. **onsemi** does not convey any license under its patent rights nor the rights of others.

onsemi, **Onsemi**, and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "**onsemi**" or its affiliates and/or subsidiaries in the United States and/or other countries. **onsemi** owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of **onsemi**'s product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. **onsemi** reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and **onsemi** makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does **onsemi** assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using **onsemi** products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by **onsemi**. "Typical" parameters which may be provided in **onsemi** data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. **onsemi** does not convey any license under any of its intellectual property rights nor the rights of others. **onsemi** products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use **onsemi** products for any such unintended or unauthorized application, Buyer shall indemnify and hold **onsemi** and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that **onsemi** was negligent regarding the design or manufacture of the part. **onsemi** is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

ADDITIONAL INFORMATION

TECHNICAL PUBLICATIONS:

Technical Library: www.onsemi.com/design/resources/technical-documentation
onsemi Website: www.onsemi.com

ONLINE SUPPORT: www.onsemi.com/support

For additional information, please contact your local Sales Representative at
www.onsemi.com/support/sales